



Advances in Additive Manufacturing Technology

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Deadline for manuscript
submissions:

closed (15 March 2022)

Message from the Guest Editor

Additive manufacturing (AM) has arisen as a flexible innovation platform and turned into an influential strategy for future modern manufacturing systems. Various methods of AM have been developed to meet the demands for the fabrication of complex structures with high resolution. However, there are still some challenges that could slow down the opportunities of AM. Therefore, demanding a clear understanding of causes and finding the possible solutions can accelerate the efficiency and productivity of AM technology in the future.

We invite the submission with topics including, but are not limited to, the following:

- Novel AM approaches and technologies to improve quality and efficiency;
- Recent developments in materials and their effects on AM process and part properties;
- Theoretical and experimental research, knowledge, and new ideas in design for AM;
- Research and development in 3D printing of advanced smart and multifunctional materials;
- Mathematical modeling or numerical simulation to predict the optimal operational parameters for various AM techniques;
- The latest development of test methods including mechanical and microstructural analysis of AM fabricated parts.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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